2A, 200V Ultra Fast Surface Mount Rectifier

FEATURES

• AEC-Q101 qualified

TAIWAN

• Glass passivated chip junction

SEMICONDUCTOR

- Ideal for automated placement
- Low profile package
- Ultra Fast recovery time for high efficiency
- Moisture sensitivity level: level 1, per J-STD-020
- RoHS Compliant
- Halogen-free according to IEC 61249-2-21

APPLICATIONS

- DC to DC converter
- Automotive application
- Car lighting
- Snubber
- Freewheeling application

MECHANICAL DATA

- Case: DO-214AA (SMB)
- Molding compound meets UL 94V-0 flammability rating
- Terminal: Matte tin plated leads, solderable per J-STD-002
- Meet JESD 201 class 2 whisker test
- Polarity: Indicated by cathode band
- Weight: 0.090g (approximately)

KEY PARAMETERS		
PARAMETER	VALUE	UNIT
I _F	2	А
V _{RRM}	200	V
I _{FSM}	50	А
T _{J MAX}	150	°C
Package	DO-214AA (SMB)	
Configuration	Single die	



ABSOLUTE MAXIMUM RATINGS (T _A = 25°C unless otherwise noted)			
PARAMETER	SYMBOL	ES2DVH	UNIT
Marking code on the device		ES2DV	
Repetitive peak reverse voltage	V _{RRM}	200	V
Reverse voltage, total rms value	V _{R(RMS)}	140	V
Forward current	I _F	2	А
Surge peak forward current, 8.3ms single half sine-wave superimposed on rated load	I _{FSM}	50	A
Junction temperature	TJ	- 55 to +150	°C
Storage temperature	T _{STG}	- 55 to +150	°C



THERMAL PERFORMANCE			
PARAMETER	SYMBOL	ТҮР	UNIT
Junction-to-lead thermal resistance	R _{ejl}	25	°C/W
Junction-to-ambient thermal resistance	R _{eja}	75	°C/W

ELECTRICAL SPECIFICATIONS (T _A = 25°C unless otherwise noted)					
PARAMETER	CONDITIONS	SYMBOL	ТҮР	MAX	UNIT
Forward voltage ⁽¹⁾	I _F = 2A, T _J = 25°C	V _F	-	0.9	V
Reverse current @ rated $V_R^{(2)}$	$T_J = 25^{\circ}C$	I _R	-	10	μA
	T _J = 150°C		-	350	μA
Junction capacitance	$1 MHz, V_R = 4.0 V$	CJ	25	-	pF
Reverse recovery time	$I_F = 0.5A, I_R = 1.0A, I_{rr} = 0.25A$	t _{rr}	-	20	ns

Notes:

1. Pulse test with PW = 0.3ms

2. Pulse test with PW = 30ms

ORDERING INFORMATION		
ORDERING CODE	PACKAGE	PACKING
ES2DVH	DO-214AA (SMB)	3,000 / Tape & Reel



CHARACTERISTICS CURVES

(T_A = 25°C unless otherwise noted)

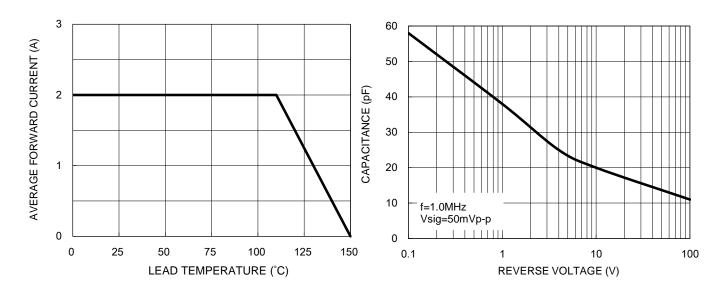


Fig.1 Forward Current Derating Curve

Fig.3 Typical Reverse Characteristics

Fig.4 Typical Forward Characteristics

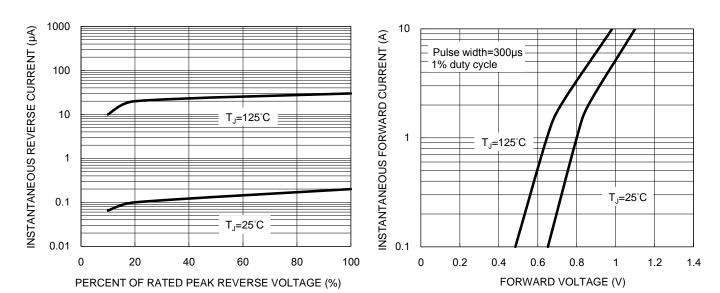


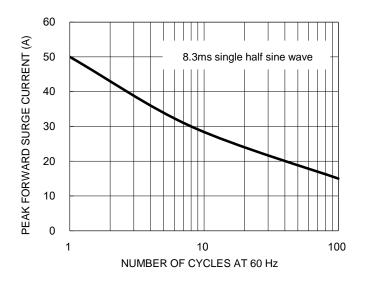
Fig.2 Typical Junction Capacitance



CHARACTERISTICS CURVES

 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$

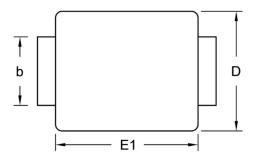
Fig.5 Maximum Non-repetitive Forward Surge Current

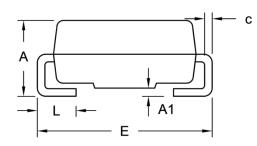




PACKAGE OUTLINE DIMENSIONS

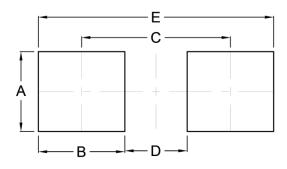
DO-214AA (SMB)





DIM.	Unit	(mm)	Unit	(inch)
	Min.	Max.	Min.	Max.
A	1.95	2.65	0.077	0.104
A1	0.05	0.20	0.002	0.008
b	1.95	2.20	0.077	0.087
с	0.15	0.31	0.006	0.012
D	3.30	3.95	0.130	0.156
E	5.10	5.60	0.201	0.220
E1	4.05	4.60	0.159	0.181
L	0.75	1.60	0.030	0.063

SUGGESTED PAD LAYOUT



Symbol	Unit (mm)	Unit (inch)
A	2.30	0.091
В	2.50	0.098
С	4.30	0.169
D	1.80	0.071
E	6.80	0.268

MARKING DIAGRAM



P/N	= Marking Code
G	= Green Compound

YW = Date Code

F = Factory Code



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